Tapes Adwill series

Adwill will give you the Advantage

LE series

Dicing Die-Bonding Tape

Adwill LE Tape is a high value-adding tape, combining the functions of dicing tape and die-bonding material. Other than die attach paste, it prevents adhesive bleed-out or uneven distribution by transferring the adhesive uniformly onto the backside of the die at pick-up. Adwill LE Tape is particularly suited for die-bonding of thick stacked CSPs.

Processing is also simplified since the same tape can be used in the process from dicing to bonding. Three different types of LE Tape are available for the following applications:

- Die-to-die
- Die-to substrate
- Die-to-die FOW (Film On Wire)



Application	Dicing Method	LE-Layer Thickness	Type	Tape Name
Die-to-die	Plasma, Blade	10 µm	Heat curing	LE04-10
	Plasma, Blade	20 µm	Heat curing	LE5000S
	Blade	20 µm	No Heat curing	LE4424
Die-to-substrate	Plasma	20 µm	Heat curing	LE5000S
FOW (Film On Wire)	Blade	75 µm	Heat curing	LE4777H

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